

**In the Specification:**

On page 1 of the specification, under "Cross-Reference to Related Applications," please replace the first paragraph to appear as follows:

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A<sup>1</sup>  
This application claims priority under 35 U.S.C. § 119(e) to U.S. Provisional Patent Applications Serial No. 60/160,482, which was filed on October 19, 1999. In addition, the subject matter disclosed herein is related to the subject matter disclosed in copending Application Ser. No. 09/692,529 (~~Attorney Docket Number BERG-2547/C2648~~), filed on October 19, 2000. Both applications are herein incorporated by reference.

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On page 5 of the specification, please replace the paragraph beginning on line 19 and ending on line 20 to appear as follows:

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A<sup>2</sup>  
Figures 8A-8C show a portion of a substrate so as to illustrate the self-centering characteristics of the inventive connector.

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On page 7 of the specification, please replace the first full paragraph beginning on line 6 and ending on line 11 to appear as follows:

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A<sup>3</sup>  
In a manner similar to that described in International Publication number WO 98/15991, pockets on the bottom surface of wafer 311 can receive solder paste (not shown) provided during a squeegee operation. Thereafter, the pockets now filled with solder paste can